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ABSTRACT OF THE DISCLOSURE

2           We have discovered a method of reducing the effect of material sputtered/etched  
3       during the preheating of a substrate. One embodiment of the method pertains to preheating  
4       a substrate which includes a metal-containing layer which is to be pattern etched subsequent  
5       to preheating. The method includes exposing the substrate to a preheating plasma which  
6       produces a deposit or residue during preheating which is more easily etched than said metal-  
7       containing layer during the subsequent plasma etching of said metal-containing layer.

09747657.122200